

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently amended) An apparatus comprising:
an embossable substrate mixture that includes a polymer and a release agent;
a substrate base, wherein the embossable substrate mixture is a film over the substrate
base and is embossed;
metal wiring deposited in embossed grooves of the embossable substrate mixture; and
one or more electronic chips coupled to the metal wiring.
2. (Canceled).
3. (Currently amended) The apparatus of claim 1 [[2]], wherein the embossable substrate mixture is a film over a polyester ~~Mylar~~ film that is attached to the substrate base.
4. (Original) The apparatus of claim 1, wherein the embossable substrate mixture polymer comprises:
an epoxy resin; and
a hardening agent.
5. (Currently amended) The apparatus of claim 1 [[4]], wherein the release agent comprises carnauba wax.
6. (Currently amended). The apparatus of claim 1 [[5]], further comprising:
one or more external electrical connections coupled to the metal wiring.

7. (Original) The apparatus of claim 6, wherein the one or more electronic chips attached to the metal wiring includes a computer processor; the apparatus further comprising:

- a memory operatively coupled to the processor;
- an input system and an output system operatively coupled to the processor;
- a power supply operatively coupled to the processor; and
- an enclosure holding the processor, the memory, the input system, the output system, and the power supply.

8. (Original) The apparatus of claim 1, wherein the release agent comprises one or more components selected from the group consisting of montanic acid, stearic acid, myristic acid, and combinations thereof.

9. (Original) The apparatus of claim 1, wherein the release agent comprises one or more components selected from the group consisting of fatty acid glycol esters, polyethylene glycol esters, laurate ester and combinations thereof.

10. (Original) The apparatus of claim 1, wherein the release agent comprises one or more components selected from the group consisting of microcrystalline wax, urethanized microcrystalline wax and oxidized microcrystalline wax and combinations thereof.

11. (Original) The apparatus of claim 1, wherein the release agent comprises one or more components selected from the group consisting of polyethylene waxes, urethanized polyethylene and oxidized polyethylene wax and combinations thereof.

12. (Original) The apparatus of claim 1, wherein the release agent comprises one or more components selected from the group consisting of low-molecular-weight branched polyethylene, oxidized low-molecular-weight branched polyethylene, silicone, amino functional polydimethylsiloxanes, and combinations thereof.

13. (Currently amended) An apparatus comprising: an embossable substrate mixture that includes a polymer and a release agent ~~The apparatus of claim 1~~, wherein the substrate mixture comprises:

- methyl ethyl ketone;
- diglycidyl Bisphenol-A;
- tetrabromo Bisphenol-A;
- ortho-cresol novolak epoxy resin;
- epoxy-terminated polybutadiene rubber;
- brominated phenolic novolak resin;
- 2,4-diamino-6-(2-methyl-1-imadizolyethyl)-1,3,5-triazine.isocyanuric acid adduct;
- silica; and
- carnauba wax.

14. (Currently amended) An apparatus comprising: an embossable substrate mixture that includes a polymer and a release agent ~~The apparatus of claim 1~~, wherein the substrate mixture has a composition ratio of approximately:

- 210 parts of methyl ethyl ketone;
- 20 parts of diglycidyl Bisphenol-A;
- 20 parts of tetrabromo Bisphenol-A;
- 20 parts of ortho-cresol novolak epoxy resin (215 g/eq);
- 15 parts of epoxy-terminated polybutadiene rubber;
- 50 parts of brominated phenolic novolak resin;
- 4 parts of 2,4-diamino-6-(2-methyl-1-imadizolyethyl)-1,3,5-triazine.isocyanuric acid adduct;
- 11 parts of silica (maximum particle size of 5 microns); and
- 1 part of carnauba wax.

15. (Original) The apparatus of claim 14, further comprising:
metal wiring deposited in embossed grooves of the embossable substrate mixture;
one or more electronic chips coupled to the metal wiring, wherein the one or more
electronic chips form a computer processor;
one or more external electrical connections coupled to the metal wiring;
a memory operatively coupled to the processor;
an input system and an output system operatively coupled to the processor;
a power supply operatively coupled to the processor; and
an enclosure holding the processor, the memory, the input system, the output system, and
the power supply.

16. - 20. (Canceled)

21. (Currently amended) An apparatus comprising:
a substrate base; ~~and~~
means attached to the substrate base for providing an embossable surface with reduced
adherence properties to an embossing tool wherein the means attached to the substrate base for
providing the embossable surface is embossed;
metal wiring deposited in embossed grooves of the embossable surface; and
one or more electronic chips coupled to the metal wiring, wherein the one or more
electronic chips form a computer processor.

22. (Original) The apparatus of claim 21, wherein the means for providing the embossable
surface includes a polymer film having attached thereto means for releasing the embossing tool
mixed with an epoxy resin.

23. (Original) The apparatus of claim 22, wherein the means for releasing the embossing tool
comprises carnauba wax.

24. (Currently amended) The apparatus of claim 23, ~~wherein the means attached to the substrate base for providing the embossable surface is embossed; wherein the apparatus further comprises:~~

- ~~metal wiring deposited in embossed grooves of the embossable surface;~~
- ~~one or more electronic chips coupled to the metal wiring, wherein the one or more electronic chips form a computer processor;~~
- one or more external electrical connections coupled to the metal wiring;
- a memory operatively coupled to the processor;
- an input system and an output system operatively coupled to the processor;
- a power supply operatively coupled to the processor; and
- an enclosure holding the processor, the memory, the input system, the output system, and the power supply.

25. - 28. (Canceled)